# DICING METHOD

## ABSTRACT

With the invented dicing method, by increasing the cohesive strength while decreasing the adhesive strength of an ultraviolet-curing adhesive in advance, mixing of the ultraviolet-curing adhesive layer of an adhesive sheet with a die attach film on a dicing line can be decreased and pickup failures can be reduced, when picking up chips having a die attach film after dicing. The dicing method for a semiconductor wafer with a die-attach film comprises a first gluing step in which a die attach film is affixed to an adhesive sheet having an ultraviolet-curing adhesive laminated on a base material film, a second gluing step in which a semiconductor wafer is affixed to the opposite side of the die attach film affixed to the adhesive sheet, an ultraviolet irradiation step in which the ultraviolet-curing adhesive is irradiated with ultraviolet light, and a dicing step in which the semiconductor wafer and the die attach film affixed to the adhesive sheet are diced.